Uniformity Monitoring of Photoresist Etching using Multi-Channel Endpoint Detection in Inductively Coupled Plasma

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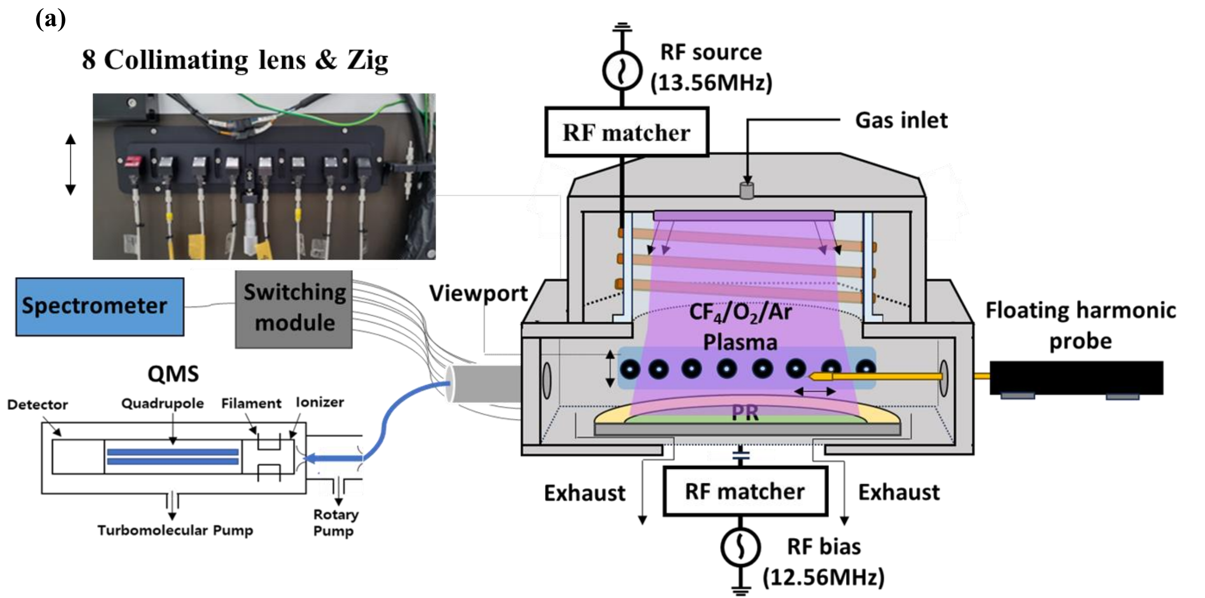
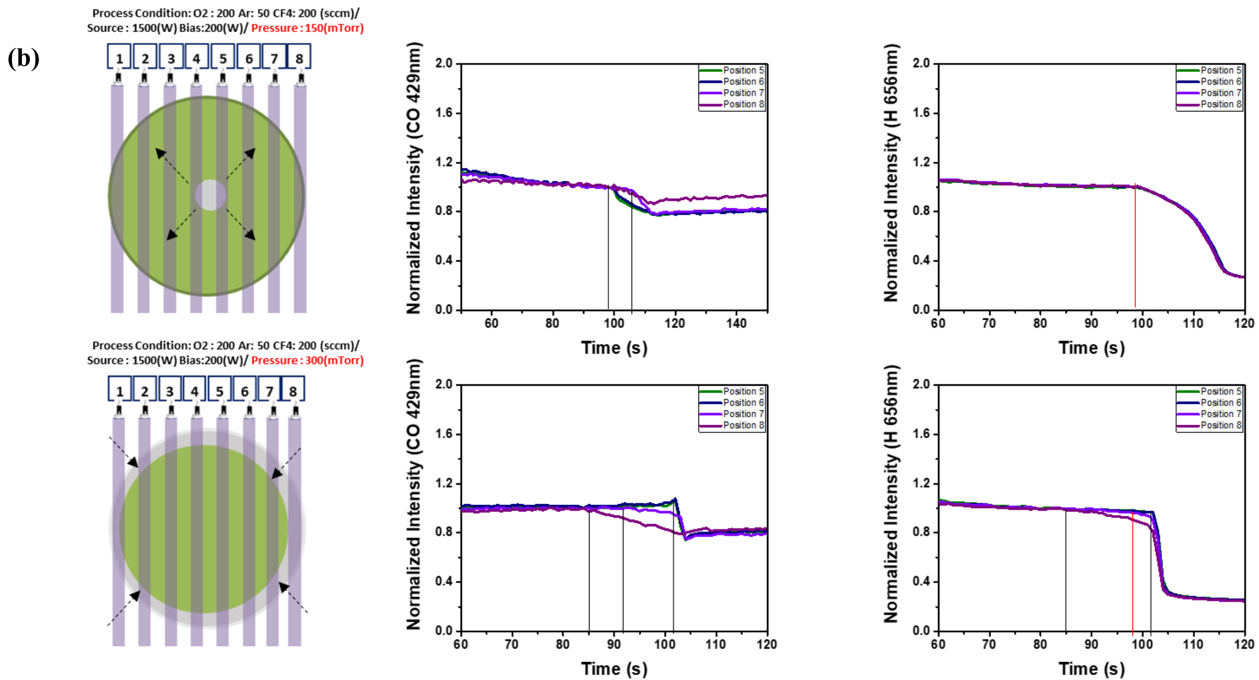
(a)



(b)



(c)

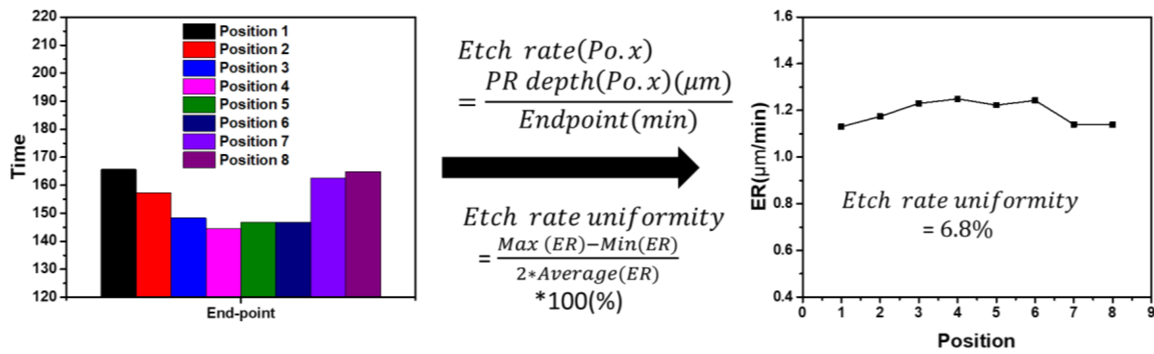


Fig. 1. (a) Scheme of the 8-channel OES system on 300mm descum chamber /(b) Areas Detected by 8 Channels with Normalized Multi-Channel Endpoint Patterns under Center and Edge High Etch Rate Conditions (c) Uniformity measurement from multi-endpoint detection

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